



Standard solderable coating

FOR HIGH-PRECISION HERMETIC PACKAGING

Solderable metal coatings are durable and resist to high temperature and harsh environmental conditions. They provide the highest quality sealing for hermetic packaging.

Both Physical Vapor Deposition (PVD) and electroplating belong to Blösch's portfolio of metallization technologies.

Our PVD coating processes are optimized for depositing stacks of metals and alloys.

Our electroplating processes enable the deposition of thick metals layers.

The combination of PVD and electroplating provides unique capability and features for many applications.

Key features

- Solderable coating solutions for the edge of optical windows or lenses.
- The edge solderable coating solution enables much design flexibility, for easy integration on a metal support.
- Ideal coating solution for most hermetic windows or lenses.
- Flat or other surface shapes can be coated.
- Substrates may be either sapphire, fused silica, or most crystals, glasses and ceramics.
- The windows or lenses can also be anti-reflection coated.

Markets

- Medical & Food
- Sensing
- Aerospace & Defense
- Telecom
- Environmental
- Other applications

Technical data

- Substrates: Sapphire, Fused silica, other crystals and glasses, ...
- All forms and shapes, including flat and 3D substrates
- State-of-the-art and proven vacuum deposition and electroplating technologies
- Substrate size: from a few millimeters dimensions up to several hundreds of millimeters
- Specifications for surface cleanliness and roughness apply
- Solderable layer for either AuSn or AgSn solders
- Adhesive strength > 10 N/mm²
- Shear strength > 4 N/mm²
- Sheet resistance < 0.1 Ohm/sq.
- MIL-M-13508C 4.4.6 / 4.4.7

